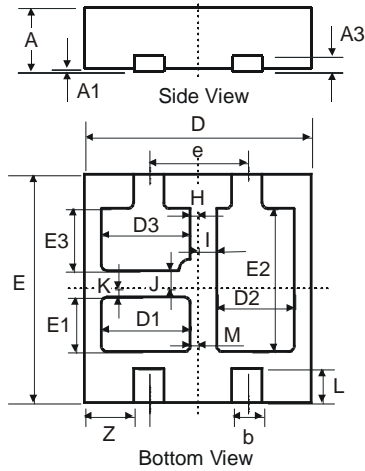


**Package Outline Dimensions**

**U-DFN3030-4**

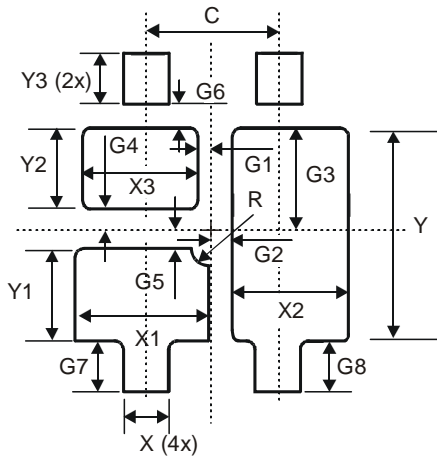


U-DFN3030-4							
Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.57	0.63	0.60	E1	0.615	0.815	0.715
A1	0	0.05	0.02	E2	1.78	1.98	1.88
A3	-	-	0.15	E3	0.715	0.915	0.815
B	0.35	0.45	0.40	H	0.05	0.15	0.10
D	2.90	3.10	3.00	I	0.20	0.30	0.25
D1	1.075	1.275	1.175	J	0.185	0.285	0.235
D2	0.925	1.125	1.025	K	0.065	0.165	0.115
D3	1.075	1.275	1.175	L	0.30	0.60	0.45
E	2.90	3.10	3.00	M	0.05	0.15	0.10
e	-	-	1.30	Z	-	-	0.65

**All Dimensions in mm**

**Suggested Pad Layout**

**U-DFN3030-4**



Dimensions	Value (in mm)
C	1.300
G1	0.100
G2	0.150
G3	0.830
G4	0.115
G5	0.135
G6	0.170
G7	0.500
G8	0.500
R	0.150
X	0.500
X1	1.375
X2	1.225
X3	1.175
Y	1.980
Y1	1.015
Y2	0.715
Y3	0.650

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.